

Welcome to O-leading

We are professional PCB manufacturer with more than ten years experiences . Products range-single, double side ,multi-layer PCB ,flexible PCB and MCPCB.We can provide fast prototype service - S/S in 24hrs , 4-8layers in 48-96 working hrs production time.

[\(Ceramic PCB manufacturer china\)](#)

COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED

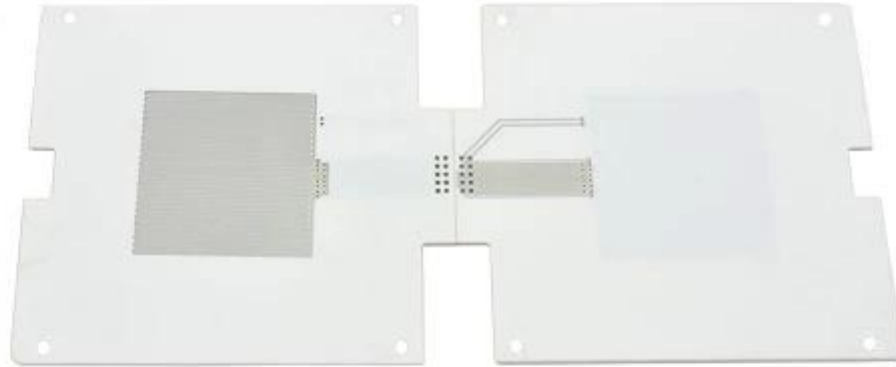
Pack with colorless transparent bubble film ,25 PCS/ bag, put desiccant in flank, put humidity indicator card on top side

PLEASE CLICK HERE FOR MORE INFORMATION:

Product Description

PCB P/N	Q508756-C
Layer Count	2L
Material	Base Ceramics
Board thk	0.55mm
copper thk	1/1oz
Smalleat hole size	1.6mm
No. of holes (pcs)	4
line w/s	1.27mm
Impedance control. Y / N (Tol %)	N
Surface Finishing	ENIG
Solder Mask Silkscreen	N/A
Single board size	Dim X (mm):50;Dim Y (mm):55
Panelisation	Dim X (mm):50;Dim Y (mm):55;No Of UPS:1
Special:peelable mask	N
Routing/Punching	CNC

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[High Frequency PCB wholesales china](#)

Our Team





Certifications



201726 201VZL430354 - Wiring, Printed - Component



ZPMV2.E490354
Wiring, Printed - Component

For enhanced search functionality, please visit UL's [ULi Family of Databases](#).
Click on a product designation for complete information.

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Wiring, Printed - Component

See General Information for Wiring, Printed - Components

O-LEADING SUPPLY CHAIN CO LIMITED

E490354

Fortune Building, Nanheng West Road
Room 1313
Huizhou, Guangdong 516211, CHINA

	Cond Width			SS/ DS/ Diam	Area	Solder		Flame	RoHS	C	
	Min	Max	Min			Max	Temp				Class
Min	Edge	Thk	DS/ Diam	Solder	Dper	Flame	UL796	T			
Typ	max(in)	mm(in)	mic(mil)	DSO	mm(in)	C	sec	C	Class	DSR	I
Multi-layer (mass laminate) printed wiring boards.											
O-LEADING-401											
	0.2 (0.004)	0.3 (0.012)	34 (1.34)	D6	12.7 (0.5)	260	10	130	V-0	-	-
O-LEADING-407											
	0.08 (0.003)	0.2 (0.008)	17 (0.67)	D5	9.2 (0.4)	260	10	130	V-0	NI	-
Multi-layer printed wiring boards.											
O-LEADING-408											
	0.125 (0.005)	0.125 (0.005)	12 (0.47) min:1.25	D6	50.8 (2.0)	260	20	130	V-0	NI	*
Single layer printed wiring boards.											
O-LEADING-002											
	0.76 (0.015)	1.14 (0.045)	34 (1.34)	S5	19.1 (0.8)	260	10	105	V-0	NI	-
O-LEADING-003											
	0.38 (0.015)	1.14 (0.045)	34 (1.34)	S5	19.1 (0.8)	260	10	130	V-0	▲	-
O-LEADING-033											
	0.15 (0.006)	0.3 (0.012)	34 (1.34)	S5	25.4 (1.0)	260	10	120	V-0	NI	-
O-LEADING-205											
	0.1 (0.004)	0.3 (0.012)	34 (1.34)	D6	69.6 (2.7)	260	10	130	V-0	NI	-
O-LEADING-206											
	0.15 (0.006)	0.33 (0.013)	17 (0.67)	D5	69.6 (2.7)	260	10	130	V-0	NI	-

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.
Last updated on 2017-01-27

Questions? [Print this page](#) [Terms of Use](#) [Page Top](#)

[http://www.ul.com/ulcertification/UL60718RMS/ewg/ulcert/ZPMV2.E490354/Component/Wiring,Printed-Component/10](#)



Test Report

No. CANEC1805164701

Date: 03 Apr 2018

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Test Results:

Test Part Description:

Specimen No. **SGS Sample ID** **Description**
SNI CAN18-051647.001 Green "PCB"

Remarks:

- (1) 1 mg/kg = 1 ppm = 0.0001%
- (2) MDL = Method Detection Limit
- (3) ND = Not Detected (< MDL)
- (4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method: With reference to IEC 62321-4:2014+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	Det
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	9
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (CrVI)	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tribromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tribromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND



SGS is pleased to announce the launch of its new online reporting system, which allows clients to view their test results online at any time. This system is designed to provide a secure and efficient way for clients to access their test results. For more information, please contact your account manager or visit [www.sgs.com](#).

Member of the SGS Group (SGL SA)

Packaging & Delivery

Packaging Details	16 years professional OEM pcb board manufacturer
Delivery Detail	7-12days



FAQ

1. How do O-Leading ensure quality? [Ceramic Flash Gold wholesales](#)

Our high quality standard is achieved with the following.

- 1.The process is strictly controlled under ISO 9001:2008 standards.
- 2.Extensive use of software in managing the production process
- 3.State-of-art testing equipments and tools. E.g. Flying Probe, X-ray Inspection, AOI (Automated Optical Inspector) and ICT (in-circuit testing).
- 4.Dedicated quality assurance team with failure case analysis process
- 5.Continuous staff training and education

2. How do O-Leading keep your price competitive?

Over the last decade, prices of many raw materials (e.g. copper, chemicals) had doubled, tripled or quadrupled; Chinese currency RMB had appreciated 31% over US dollar; And our labor cost also increased significantly. However, O-Leading have kept our pricing steady. This owns entirely to our innovations in reducing cost, avoiding wastes and improving efficiency. Our prices are very competitive in the industry at the same quality level.

We believe in a win-win partnership with our customers. Our partnership will be mutually beneficial if we can provide you an edge on cost and quality.

3. What kinds of boards can O-Leading process?

Common FR4, high-TG and halogen-free boards, Rogers, Arlon, Telfon, aluminum/copper-based boards, PI, etc.

4. What data are needed for PCB production?

It is best to provide data in Gerber 274-X format. In addition, Cam350, CAD, Protel 99se, PADS, DXP and Eagle can also be processed.

5. What's the typical process flow for multi-layer PCB?

Material cutting → Inner dry film → inner etching → Inner AOI → Multi-bond → Layer stack up Pressing → Drilling → PTH → Panel Plating → Outer Dry Film → Pattern Plating → Outer etching → Outer AOI → Solder Mask → Component Mark → Surface finish → Routing → E/T → Visual Inspection.